

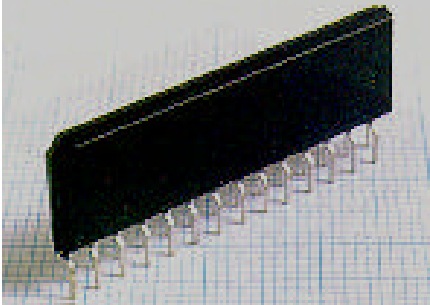
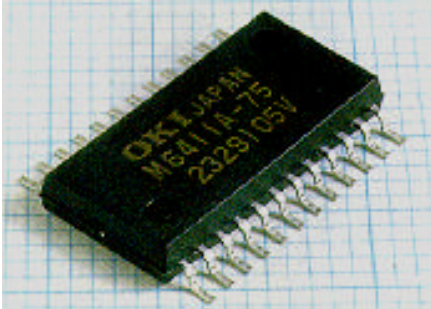
1. Memory

➡ PKG

DIP	* DUAL IN-LINE PACKAGE PIN PKG LEAD가 . LEAD PITCH 100 MIL (2.54mm), PKG WIDTH 300/400/600 MIL (PIN HOLE WIDTH), PIN 6 - 64 
P-DIP	* PLASTIC DIP MOLD ()가 PLASTIC(EPOXY COMPOUND) DIP
C-DIP	* CERAMIC DIP CERAMIC DIP. LEAD, BODY, CAP , GLASS (SEALING). 8 - 42 PIN.
SDIP	* SHRINK DIP P-DIP LEAD PITCH 가 70 MIL (1.778 mm).
SK-DIP	* SKINNY DIP P-DIP PKG WIDTH 가 600MIL PKG 300MIL .
SIP	* SINGLE IN-LINE PACKAGE LEAD 가 PKG PCB PKG . LEAD PITCH 100 MIL. 2 - 23 PIN.

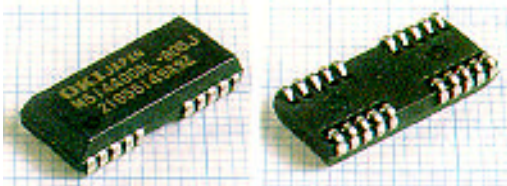
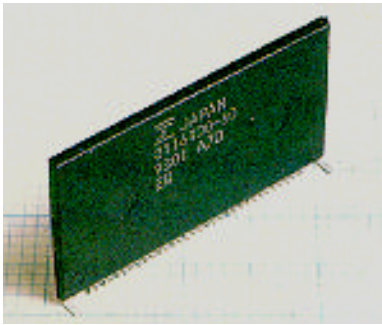
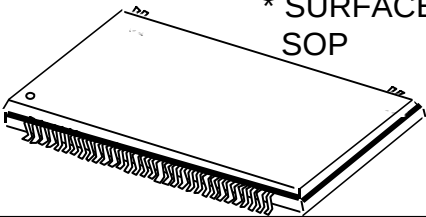
1. Memory

➡ PKG ()

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SSIP	* SHRINK SIP LEAD PITCH 가 70 MIL SIP
ZIP (VDIP)	* ZIG-ZAG IN-LINE PACKAGE (VETICAL DIP) SIP PKG LEAD 가 , ZIG-ZAG FORMING . LEAD PITCH 100 MIL. 
SOP	* SMALL OUTLINE PACKAGE PKG GULL-FORM LEAD 가 PKG. LEAD PITCH 50 MIL(1.27 mm). 8 - 44 PIN. 
SSOP	* SHRINK SOP LEAD PITCH 가 1.0/0.8/0.65/0.5 mm SOP 8 - 80 PIN.

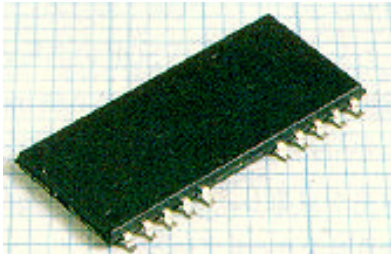
1. Memory

➡ PKG ()

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SOJ	* SMALL OUTLINE J-LEADED PACKAGE SOP LEAD 가 J FORMING PKG. LEAD PITCH 50 MIL. 20 - 40 PIN. 
SOI	* SMALL OUTLINE I-LEADED PACKAGE SOP/SOJ , LEAD 가 I FORMING .
SVP (VPAK)	* SURFACE VERTICAL PACKAGE SIP LEAD가 PKG , FORMING . SOJ 1/7, ZIP 1/3 . LEAD PITCH 0.5/0.65 mm. 24 - 32 PIN. T.I 가 VPAK , FUJITSU 가 SVP .  
SHP	* SURFACE HORIZONTAL PACKAGE SOP LEAD PIN PCB PKG. 

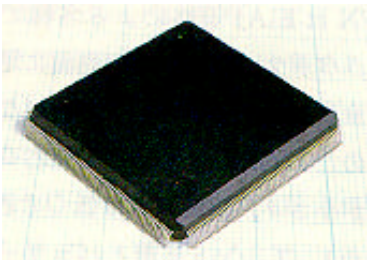
1. Memory

➡ PKG ()

TSOP	* THIN SOP 가 50 MIL , LEAD PITCH 가 50 MIL SOP. EIAJ PKG LEAD가 TSOP I , TSOP II . TYPE I 0.6/0.55/0.5 mm PITCH 가 가 , SOLDER . TYPE II PITCH 1.27 mm .  TSOP II
TSSOP	* THIN SHRINK SOP PKG BODY 가 1.0 mm , PITCH가 0.65/0.5 mm TSOP. 8 - 32 PIN. T.I JAPAN .
UTSOP	* ULTRA THIN SOP PKG BODY 가 0.65 mm TSOP. FUJITSU 가 .
VSOP	* VERY SOP SONY, FUJITSU, MITSUBISHI 가 SSOP .
USO	* ULTRA SMALL OUTLINE PACKAGE
SON	* SMALL OUTLINE NON-LEADED PKG FUJITSU CSP LEAD 가 PKG (QFN)

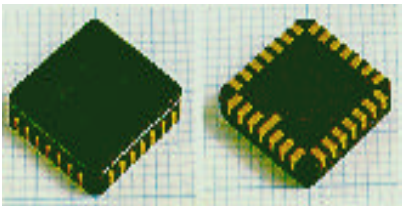
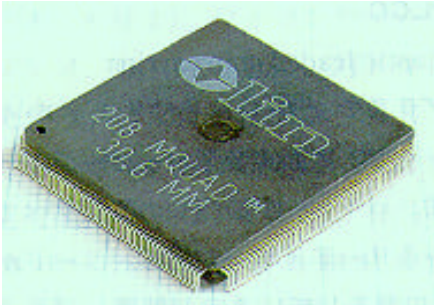
1. Memory

➡ PKG ()

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FP	* FLAT PACKAGE QFP SOP PKG.
PFP	* PLASTIC FLAT PACKAGE
QFP	* QUAD FLAT PACKAGE PKG 4 GULL-WING LEAD PIN PKG. PLASTIC, CERAMIC, METAL PLASTIC LEAD PITCH 1.0/0.8/0.65/0.5/0.4/0.3 mm 가 , 0.65 mm 232 PIN, 0.5 mm 304 PIN EIAJ 0.65 mm QFP, 0.5 mm FINE PITCH QFP .
	 PKG BODY 2.0 - 3.6mm QFP , 1.40mm LQFP 1.0 mm TQFP .
PQFP	* PLASTIC QFP
CQFP	* CERAMIC QFP
TQFP	* THIN QFP PCB 가 1.27 mm (50MIL) , BODY 가 1.0mm QFP. LEAD PITCH 0.8/0.65/0.6/0.5 mm , PIN 44 - 256 .
MQFP	* METRIC QFP JEDEC QFP . LEAD PITCH 1.0 - 0.65mm, BODY 3.8 - 2.0 QFP .

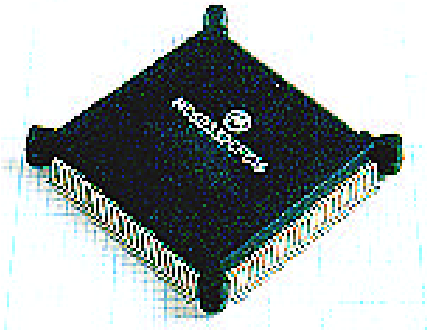
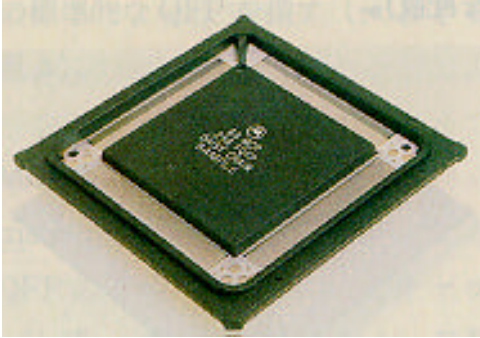
1. Memory

➡ PKG ()

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LQFP	* LOW PROFILE QFP BODY 가 1.4 mm QFP.
QFI	* QUAD FLAT I-LEADED PACKAGE LEAD 가 QFP (BUTT LEAD) MSP (MINI SQUARE PKG) QFP , LEAD PITCH 1.27 mm, PIN 18 - 68.
QFN	* QUAD FLAT NON-LEADED PACKAGE LCC , QFN EIAJ . PKG PAD가 LEAD가 . QFP 가 , CERAMIC PLASTIC , LCC CERAMIC .  PLASTIC QFN GLASS EPOXY PCB LOW COST . PITCH 1.27/0.65/0.5mm.
QTP (QTCP)	* QUAD TAPE CARRIER PACKAGE TAB TCP 4 LEAD 가 . QTP EIAJ .
MQUAD	* METAL QUAD  AI BASE CAP GLASS SEALING QFP . 2.5 - 2.8 W 가 OLIN 社 .

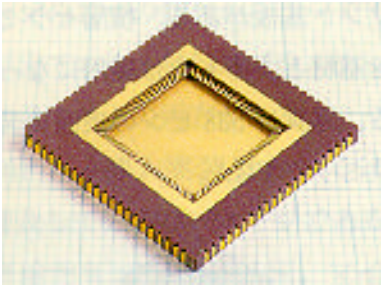
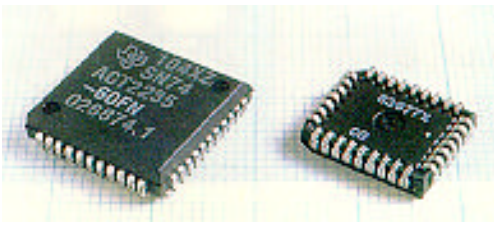
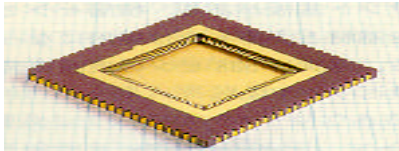
1. Memory

➡ PKG ()

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BQFP	* QFP WITH BUMPER  QFP 4 BUMPER LEAD BENT PITCH 25 MIL (0.635 mm) PIN 84 - 196.
FQFP	* FINE PITCH QFP PITCH 가 0.5 mm QFP
GQFP	* QFP WITH GUARD RING LEAD PIN LEAD BENT RING QFP.  RING LEAD GULL-FORM PCB MOTOROLA PITCH 0.5 mm , PIN 256/208.
HQFP	* QFP WITH HEAT SINK QFP HEAT SINK
PQ	* POWER QUAD QFP HEAT SINK BODY PKG
QFJ	* QUAD FLAT J-LEADED EIAJ PLCC

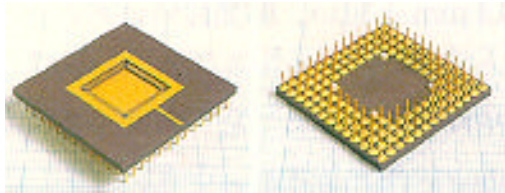
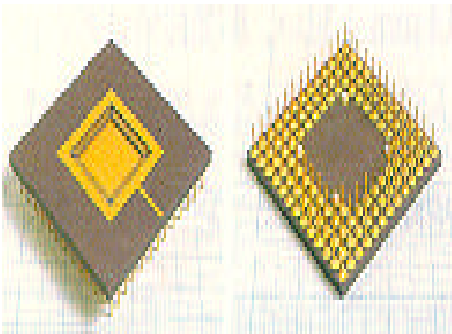
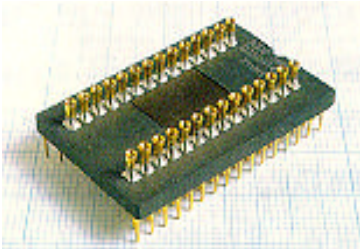
1. Memory

➡ PKG ()

LCC	* LEADELESS CHIP CARRIER CERAMIC SUBSTRATE LEAD 가 PAD 가 CERAMIC QFN QFN-C PKG. 
PLCC	* PLASTIC LEADED CHIP CARRIER PLASTIC QFJ PLASTIC LCC PITCH 1.27 mm , PIN 84 PIN 
CLCC	* CERAMIC LEADED CHIP CARRIER CERAMIC QFJ QFJ-G PKG J-FORM LEAD PITCH 1.27 mm. 
J-LCC	* J-LEADED CHIP CARRIER BULL-EYES-CAP CERAMIC QFJ.
PCLP	* PRINTED CIRCUIT BOARD LEADLESS PACKAGE, FUJITSU PLASTIC QFN PITCH 0.5/0.4 mm.

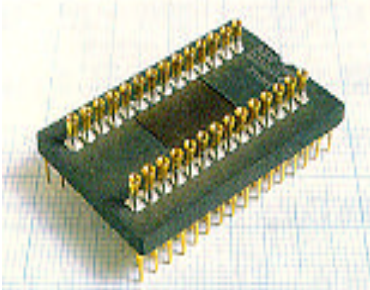
1. Memory

➡ PKG ()

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PGA	* PIN GRID ARRAY PKG LEAD PIN PIN PKG.  SUBSTRATE MULTI-LAYER CERAMIC PITCH 2.54/1.27 mm , PIN 64 - 447.
	* PAD GRID ARRAY PGA PIN PAD 가 PKG.
PPGA	* PLASTIC PGA SUBSTRATE PCB , EPOXY CHIP SEALING LOW COST PGA .
CPGA	* CERAMIC PGA
LGA	* LAND GRID ARRAY (PAD GRID ARRAY) 
PIGGY BACK	*  SOCKET CERAMIC PLASTIC PKG DIP, QFP, QFN

1. Memory

➡ PKG ()

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BGA	* BALL GRID ARRAY  PCB SOLDER BALL ARRAY PKG. CHIP , MOLD SEALING. 200 PIN PKG LEAD QFP 200 PIN 가가 . 500 PIN 가 HI-PIN PKG * PAD ARRAY CARRIER (PAC) * GLOBE TOP PAC (GPAC) * OVER MOLDED PAD ARRAY CARRIER (OMPAC)
SBGA	* SUPER BGA ANAM HI-SPEED, HI-POWER PERFO-RMANCE COPPER HEATSINK CHIP BGA
PBGA	* PLASTIC BGA LOW COST SUBSTRATE EPOXY
CBGA	* CERAMIC BGA
MBGA	* METAL BGA OLIN BGA , ANODIZED ALUMINIUM SUBSTRATE THIN FILM CIRCUIT / / BGA.

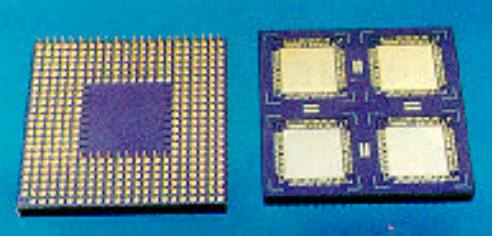
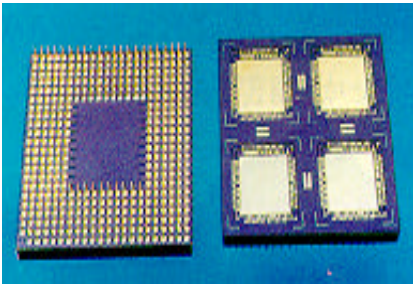
1. Memory

➡ PKG ()

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u-BGA	* MICRO BGA TESERA CHIP-SIZED PKG , HI I/O, / BGA.
TBGA	* TAPE BGA TAB BGA PKG.
mBGA	* MINI BGA FLIP CHIP SOLDER BALL DIAMETER 10 MIL, PITCH 20 MIL SANDIA NATIONAL LABORATORIES BGA MCM .
C2 BGA	* CONDUCTION COOLED BGA SGS THOMSON , , PKG. COPPER HEAT SLUG 5 WATT 가 , SYSTEM BOARD COPPER PLANE 가 .
LBGA	* LEADFRAME BGA HITACHI ,L/F SUBSTRATE LOW COST PKG.

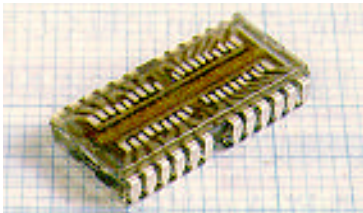
1. Memory

➡ PKG ()

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MCM	* MULTI CHIP MODULE  1 CHIP PKG. SUBSTRATE MCM-L (EPOXY),MCM-C (GLASS CERAMIC), MCM-D (ALUMINIUM) . MCM-L LOW COST , MCM-C HIC , MCM-D 가 COST 가 .
TAB	* TAPE AUTOMATED BONDING BARE CHIP , FILM LEAD CHIP
TCP	* TAPE CARRIER PACKAGE  TAB CHIP TAPE PKG TAB QFP , FINE PITCH , COB , LCD CHIP . PITCH 0.25 mm, 500 PIN 가 . LEAD 가 2 DTCP, 4 QTCP . PCB LEAD CUT FORM .

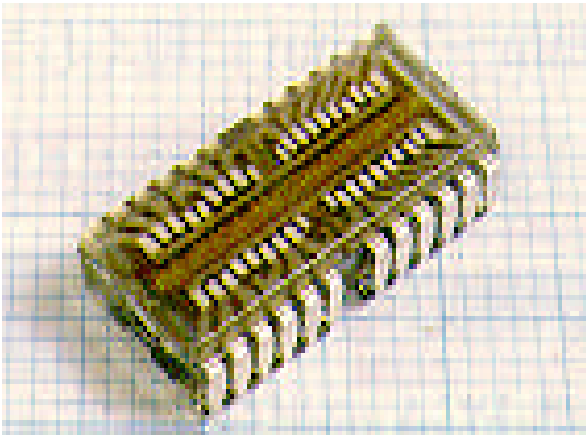
1. Memory

⇒ PKG ()

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CSP	* CHIP SCALE PACKAGE CHIP 120% PKG COG, BLP, u-SPRING .
FC	* FLIP CHIP BARE CHIP BOND PAD BUMP , PCB 가 가 PKG .
COB	* CHIP ON BOARD BARE CHIP , PCB CHIP WIRE BOND PACKAGING .
COG	* CHIP ON GLASS FLIP CHIP , SUBSTRATE 가 GLASS 가 LCD .
KGD	* KNOWN GOOD DIE WAFER LEVEL BURN , FUNCTIONAL TEST CHIP CHIP DIE.
LOC	* LEAD ON CHIP CHIP L/F INNER LEAD 가 PKG , COL PKG ACCESS TIME PKG .
	

1. Memory

➡ PKG ()

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COL	* CHIP ON LEAD LOC L/F CHIP PKG.
BLP	* BOTTOM LEADED PACKAGE CSP ,)LG JEDEC PKG. PKG PAD 가 LEAD SOJ 2 CHIP BOND PAD C-BLP (CENTER) ,S-BLP(SIDE), 3-D BLP(STACKED) TYPE APPLICATION 가 .  FUJITSU SON PKG , HI-PIN , PCB PKG .

1. Memory

⇒ PKG ()

u-SPRING	* MICRO SPRING FORMFACTOR LG CSP WF LEVEL GOOD DIE GOLD WIRE BONDING SPRING Au/Ni PLATING PKG PCB FLIP CHIP SOLDER , PCB PAD , REPAIR가 FLEXIBILITY 가 PCB 